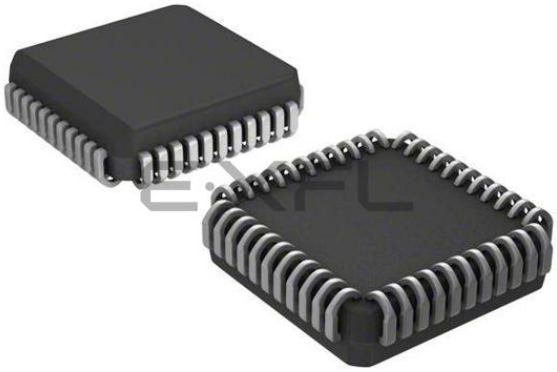

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	33MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	4KB (2K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	232 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c42a-33i-l

Table of Contents

For register and module descriptions in this data sheet, device legends show which devices apply to those sections. For example, the legend below shows that some features of only the PIC17C43, PIC17CR43, PIC17C44 are described in this section.

Applicable Devices					
42	R42	42A	43	R43	44

To Our Valued Customers

We constantly strive to improve the quality of all our products and documentation. We have spent an exceptional amount of time to ensure that these documents are correct. However, we realize that we may have missed a few things. If you find any information that is missing or appears in error from the previous version of the PIC17C4X Data Sheet (Literature Number DS30412B), please use the reader response form in the back of this data sheet to inform us. We appreciate your assistance in making this a better document.

To assist you in the use of this document, Appendix C contains a list of new information in this data sheet, while Appendix D contains information that has changed

TABLE 3-1: PINOUT DESCRIPTIONS

Name	DIP No.	PLCC No.	QFP No.	I/O/P Type	Buffer Type	Description
						PORTD is a bi-directional I/O Port.
RD0/AD8	40	43	15	I/O	TTL	This is also the upper byte of the 16-bit system bus in microprocessor mode or extended microprocessor mode or extended microcontroller mode. In multiplexed system bus configuration these pins are address output as well as data input or output.
RD1/AD9	39	42	14	I/O	TTL	
RD2/AD10	38	41	13	I/O	TTL	
RD3/AD11	37	40	12	I/O	TTL	
RD4/AD12	36	39	11	I/O	TTL	
RD5/AD13	35	38	10	I/O	TTL	
RD6/AD14	34	37	9	I/O	TTL	
RD7/AD15	33	36	8	I/O	TTL	
						PORTE is a bi-directional I/O Port.
RE0/ALE	30	32	4	I/O	TTL	In microprocessor mode or extended microcontroller mode, it is the Address Latch Enable (ALE) output. Address should be latched on the falling edge of ALE output.
RE1/$\overline{OE}$	29	31	3	I/O	TTL	In microprocessor or extended microcontroller mode, it is the Output Enable ($\overline{OE}$) control output (active low).
RE2/$\overline{WR}$	28	30	2	I/O	TTL	In microprocessor or extended microcontroller mode, it is the Write Enable ($\overline{WR}$) control output (active low).
TEST	27	29	1	I	ST	Test mode selection control input. Always tie to VSS for normal operation.
VSS	10, 31	11, 12, 33, 34	5, 6, 27, 28	P		Ground reference for logic and I/O pins.
VDD	1	1, 44	16, 17	P		Positive supply for logic and I/O pins.

Legend: I = Input only; O = Output only; I/O = Input/Output; P = Power; — = Not Used; TTL = TTL input; ST = Schmitt Trigger input.

NOTES:

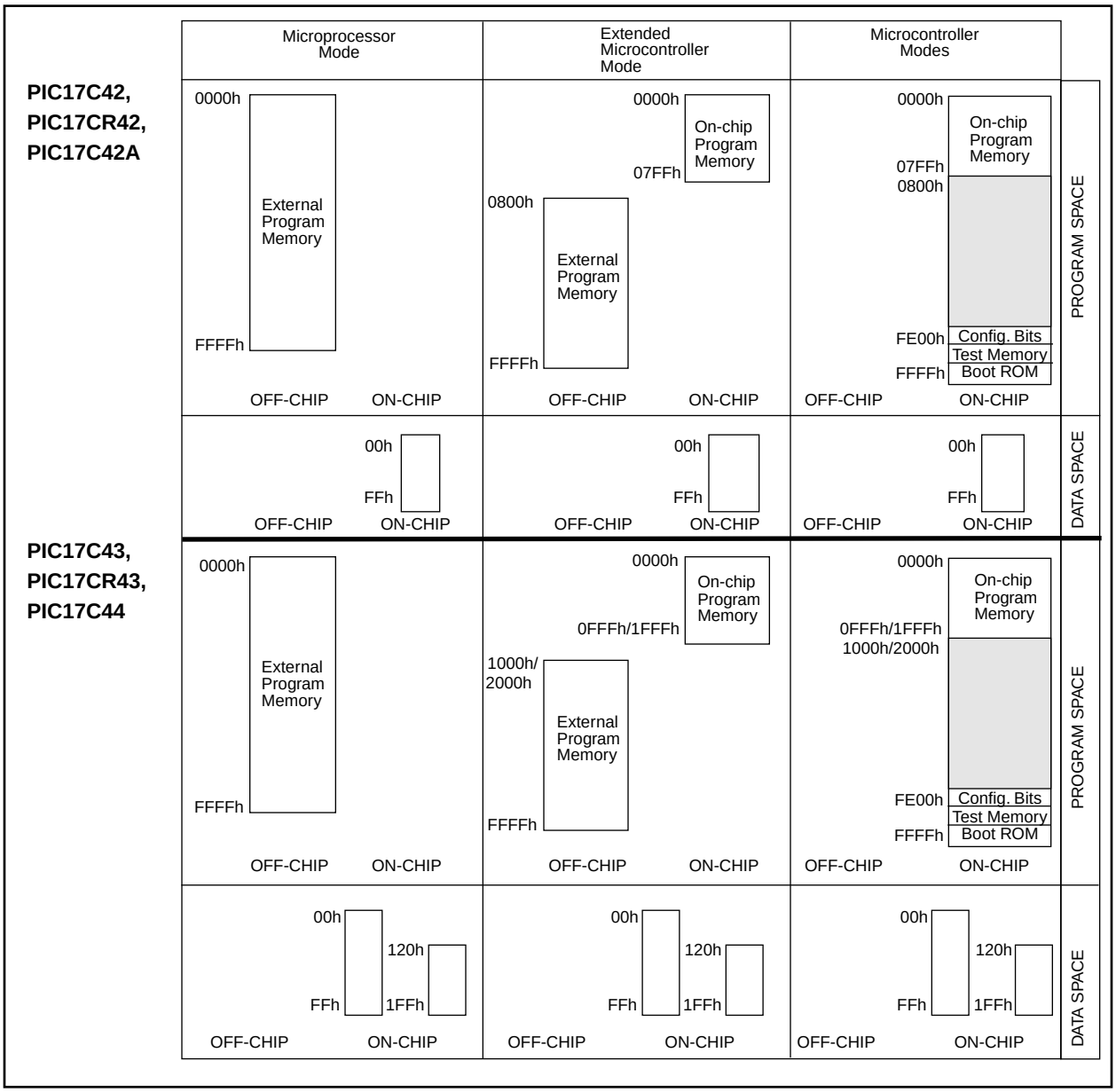
TABLE 6-1: MODE MEMORY ACCESS

Operating Mode	Internal Program Memory	Configuration Bits, Test Memory, Boot ROM
Microprocessor	No Access	No Access
Microcontroller	Access	Access
Extended Microcontroller	Access	No Access
Protected Microcontroller	Access	Access

The PIC17C4X can operate in modes where the program memory is off-chip. They are the microprocessor and extended microcontroller modes. The microprocessor mode is the default for an unprogrammed device.

Regardless of the processor mode, data memory is always on-chip.

FIGURE 6-2: MEMORY MAP IN DIFFERENT MODES



8.0 HARDWARE MULTIPLIER

All PIC17C4X devices except the PIC17C42, have an 8 x 8 hardware multiplier included in the ALU of the device. By making the multiply a hardware operation, it completes in a single instruction cycle. This is an unsigned multiply that gives a 16-bit result. The result is stored into the 16-bit PRODuct register (PRODH:PRODL). The multiplier does not affect any flags in the ALUSTA register.

Making the 8 x 8 multiplier execute in a single cycle gives the following advantages:

- Higher computational throughput
- Reduces code size requirements for multiply algorithms

The performance increase allows the device to be used in applications previously reserved for Digital Signal Processors.

Table 8-1 shows a performance comparison between the PIC17C42 and all other PIC17CXX devices, which have the single cycle hardware multiply.

Example 8-1 shows the sequence to do an 8 x 8 unsigned multiply. Only one instruction is required when one argument of the multiply is already loaded in the WREG register.

Example 8-2 shows the sequence to do an 8 x 8 signed multiply. To account for the sign bits of the arguments, each argument's most significant bit (MSb) is tested and the appropriate subtractions are done.

EXAMPLE 8-1: 8 x 8 MULTIPLY ROUTINE

```
MOVFP    ARG1, WREG
MULWF    ARG2          ; ARG1 * ARG2 ->
                       ;   PRODH:PRODL
```

EXAMPLE 8-2: 8 x 8 SIGNED MULTIPLY ROUTINE

```
MOVFP    ARG1, WREG
MULWF    ARG2          ; ARG1 * ARG2 ->
                       ;   PRODH:PRODL
BTFSC    ARG2, SB      ; Test Sign Bit
SUBWF    PRODH, F      ; PRODH = PRODH
                       ;         - ARG1
MOVFP    ARG2, WREG
BTFSC    ARG1, SB      ; Test Sign Bit
SUBWF    PRODH, F      ; PRODH = PRODH
                       ;         - ARG2
```

TABLE 8-1: PERFORMANCE COMPARISON

Routine	Device	Program Memory (Words)	Cycles (Max)	Time	
				@ 25 MHz	@ 33 MHz
8 x 8 unsigned	PIC17C42	13	69	11.04 µs	N/A
	All other PIC17CXX devices	1	1	160 ns	121 ns
8 x 8 signed	PIC17C42	—	—	—	N/A
	All other PIC17CXX devices	6	6	960 ns	727 ns
16 x 16 unsigned	PIC17C42	21	242	38.72 µs	N/A
	All other PIC17CXX devices	24	24	3.84 µs	2.91 µs
16 x 16 signed	PIC17C42	52	254	40.64 µs	N/A
	All other PIC17CXX devices	36	36	5.76 µs	4.36 µs

9.4 PORTD and DDRD Registers

PORTD is an 8-bit bi-directional port. The corresponding data direction register is DDRD. A '1' in DDRD configures the corresponding port pin as an input. A '0' in the DDRC register configures the corresponding port pin as an output. Reading PORTD reads the status of the pins, whereas writing to it will write to the port latch. PORTD is multiplexed with the system bus. When operating as the system bus, PORTD is the high order byte of the address/data bus (AD15:AD8). The timing for the system bus is shown in the Electrical Characteristics section.

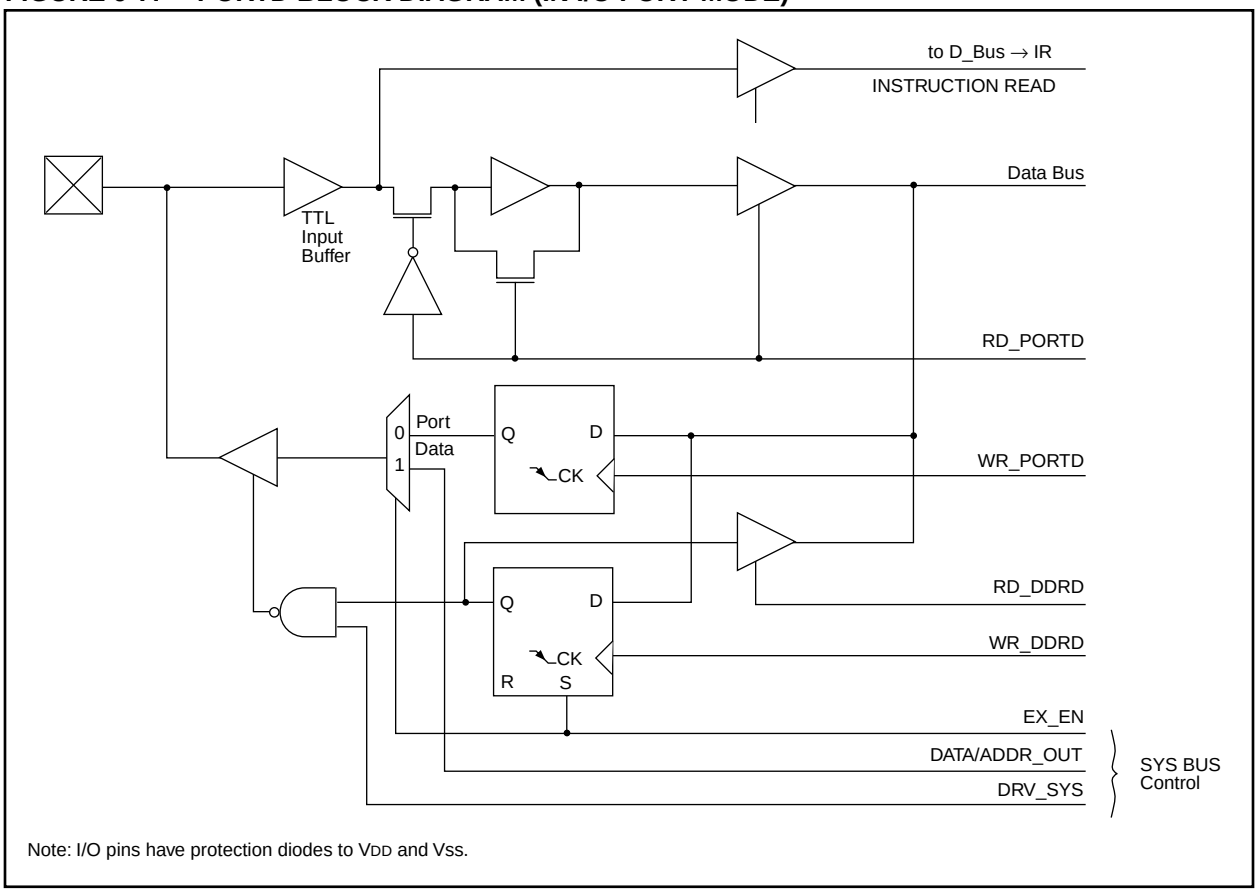
Note:	This port is configured as the system bus when the device's configuration bits are selected to Microprocessor or Extended Microcontroller modes. In the two other microcontroller modes, this port is a general purpose I/O.

Example 9-3 shows the instruction sequence to initialize PORTD. The Bank Select Register (BSR) must be selected to Bank 1 for the port to be initialized.

EXAMPLE 9-3: INITIALIZING PORTD

```
MOVLB  1          ;  Select Bank 1
CLRF   PORTD      ;  Initialize PORTD data
                  ;   latches before setting
                  ;   the data direction
                  ;   register
MOVLW  0xCF       ;  Value used to initialize
                  ;   data direction
MOVWF  DDRD       ;  Set RD<3:0> as inputs
                  ;   RD<5:4> as outputs
                  ;   RD<7:6> as inputs
```

FIGURE 9-7: PORTD BLOCK DIAGRAM (IN I/O PORT MODE)



Note: I/O pins have protection diodes to VDD and Vss.

FIGURE 14-3: CRYSTAL OPERATION, OVERTONE CRYSTALS (XT OSC CONFIGURATION)

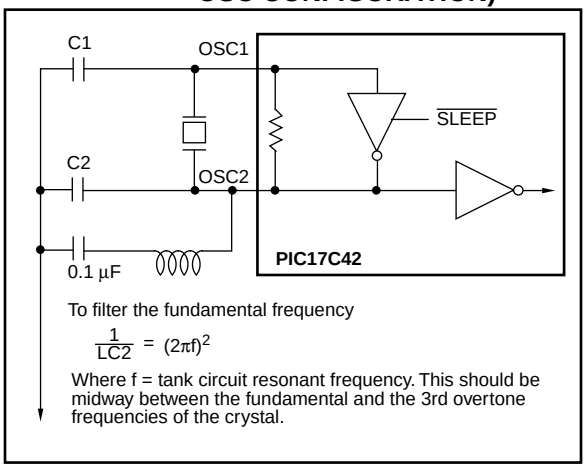


TABLE 14-2: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Oscillator Type	Resonator Frequency	Capacitor Range C1 = C2
LF	455 kHz 2.0 MHz	15 - 68 pF 10 - 33 pF
XT	4.0 MHz 8.0 MHz 16.0 MHz	22 - 68 pF 33 - 100 pF 33 - 100 pF
Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.		
Resonators Used:		
455 kHz	Panasonic EFO-A455K04B	± 0.3%
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%
Resonators used did not have built-in capacitors.		

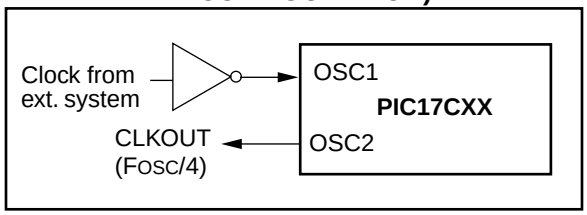
TABLE 14-3: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Freq	C1	C2
LF	32 kHz(1) 1 MHz 2 MHz	100-150 pF 10-33 pF 10-33 pF	100-150 pF 10-33 pF 10-33 pF
XT	2 MHz 4 MHz 8 MHz (2) 16 MHz 25 MHz 32 MHz (3)	47-100 pF 15-68 pF 15-47 pF TBD 15-47 pF 0 (3)	47-100 pF 15-68 pF 15-47 pF TBD 15-47 pF 0 (3)
Higher capacitance increases the stability of the oscillator but also increases the start-up time and the oscillator current. These values are for design guidance only. RS may be required in XT mode to avoid overdriving the crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values for external components. Note 1: For VDD > 4.5V, C1 = C2 ≈ 30 pF is recommended. 2: RS of 330Ω is required for a capacitor combination of 15/15 pF. 3: Only the capacitance of the board was present.			
Crystals Used:			
32.768 kHz	Epson C-001R32.768K-A	± 20 PPM	
1.0 MHz	ECS-10-13-1	± 50 PPM	
2.0 MHz	ECS-20-20-1	± 50 PPM	
4.0 MHz	ECS-40-20-1	± 50 PPM	
8.0 MHz	ECS ECS-80-S-4 ECS-80-18-1	± 50 PPM	
16.0 MHz	ECS-160-20-1	TBD	
25 MHz	CTS CTS25M	± 50 PPM	
32 MHz	CRYSTEK HF-2	± 50 PPM	

14.2.3 EXTERNAL CLOCK OSCILLATOR

In the EC oscillator mode, the OSC1 input can be driven by CMOS drivers. In this mode, the OSC1/CLKIN pin is hi-impedance and the OSC2/CLKOUT pin is the CLKOUT output (4 TOSC).

FIGURE 14-4: EXTERNAL CLOCK INPUT OPERATION (EC OSC CONFIGURATION)



MULLW **Multiply Literal with WREG**

Syntax: [*label*] MULLW k

Operands: $0 \le k \le 255$

Operation: (k x WREG) → PRODH:PRODL

Status Affected: None

Encoding:

1011	1100	kkkk	kkkk

Description: An unsigned multiplication is carried out between the contents of WREG and the 8-bit literal 'k'. The 16-bit result is placed in PRODH:PRODL register pair. PRODH contains the high byte.
WREG is unchanged.
None of the status flags are affected.
Note that neither overflow nor carry is possible in this operation. A zero result is possible but not detected.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Execute	Write registers PRODH: PRODL

Example: `MULLW 0xC4`

Before Instruction
WREG = 0xE2
PRODH = ?
PRODL = ?

After Instruction
WREG = 0xC4
PRODH = 0xAD
PRODL = 0x08

Note: This instruction is not available in the PIC17C42 device.

MULWF **Multiply WREG with f**

Syntax: [*label*] MULWF f

Operands: $0 \le f \le 255$

Operation: (WREG x f) → PRODH:PRODL

Status Affected: None

Encoding:

0011	0100	ffff	ffff

Description: An unsigned multiplication is carried out between the contents of WREG and the register file location 'f'. The 16-bit result is stored in the PRODH:PRODL register pair. PRODH contains the high byte.
Both WREG and 'f' are unchanged.
None of the status flags are affected.
Note that neither overflow nor carry is possible in this operation. A zero result is possible but not detected.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write registers PRODH: PRODL

Example: `MULWF REG`

Before Instruction
WREG = 0xC4
REG = 0xB5
PRODH = ?
PRODL = ?

After Instruction
WREG = 0xC4
REG = 0xB5
PRODH = 0x8A
PRODL = 0x94

Note: This instruction is not available in the PIC17C42 device.

RLNCF **Rotate Left f (no carry)**

Syntax: [*label*] RLNCF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

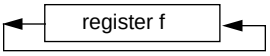
Operation: f<n> → d<n+1>;
f<7> → d<0>

Status Affected: None

Encoding:

0010	001d	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the left. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is stored back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: RLNCF REG, 1

Before Instruction
C = 0
REG = 1110 1011

After Instruction
C =
REG = 1101 0111

RRCF **Rotate Right f through Carry**

Syntax: [*label*] RRCF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

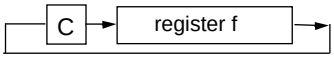
Operation: f<n> → d<n-1>;
f<0> → C;
C → d<7>

Status Affected: C

Encoding:

0001	100d	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: RRCF REG1,0

Before Instruction
REG1 = 1110 0110
C = 0

After Instruction
REG1 = 1110 0110
WREG = 0111 0011
C = 0

Applicable Devices	42	R42	42A	43	R43	44

17.0 PIC17C42 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -55 to +125˚C

Storage temperature ..... -65˚C to +150˚C

Voltage on V_{DD} with respect to V_{SS} ..... 0 to +7.5V

Voltage on $\overline{MCLR}$ with respect to V_{SS} (Note 2) ..... -0.6V to +14V

Voltage on RA2 and RA3 with respect to V_{SS} ..... -0.6V to +12V

Voltage on all other pins with respect to V_{SS} ..... -0.6V to V_{DD} + 0.6V

Total power dissipation (Note 1) 1.0W

Maximum current out of V_{SS} pin(s) - Total ..... 250 mA

Maximum current into V_{DD} pin(s) - Total ..... 200 mA

Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA

Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA

Maximum output current sunk by any I/O pin (except RA2 and RA3) ..... 35 mA

Maximum output current sunk by RA2 or RA3 pins ..... 60 mA

Maximum output current sourced by any I/O pin ..... 20 mA

Maximum current sunk by PORTA and PORTB (combined) ..... 150 mA

Maximum current sourced by PORTA and PORTB (combined) ..... 100 mA

Maximum current sunk by PORTC, PORTD and PORTE (combined) ..... 150 mA

Maximum current sourced by PORTC, PORTD and PORTE (combined) ..... 100 mA

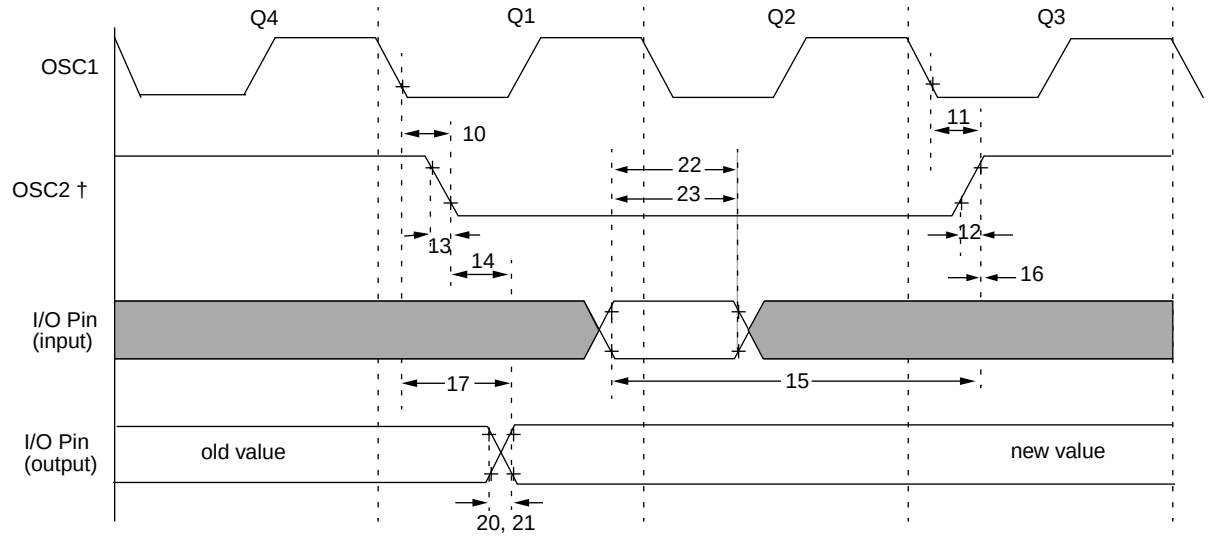
Note 1: Power dissipation is calculated as follows: $Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

Note 2: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 17-3: CLKOUT AND I/O TIMING



† In EC and RC modes only.

TABLE 17-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
10	TosH2ckL	OSC1↑ to CLKOUT↓	—	15 ‡	30 ‡	ns	Note 1
11	TosH2ckH	OSC1↑ to CLKOUT↑	—	15 ‡	30 ‡	ns	Note 1
12	TckR	CLKOUT rise time	—	5 ‡	15 ‡	ns	Note 1
13	TckF	CLKOUT fall time	—	5 ‡	15 ‡	ns	Note 1
14	TckH2ioV	CLKOUT↑ to Port out valid	—	—	0.5TCY + 20‡	ns	Note 1
15	TioV2ckH	Port in valid before CLKOUT↑	0.25TCY + 25 ‡	—	—	ns	Note 1
16	TckH2ioI	Port in hold after CLKOUT↑	0 ‡	—	—	ns	Note 1
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	—	—	100 ‡	ns	
20	TioR	Port output rise time	—	10 ‡	35 ‡	ns	
21	TioF	Port output fall time	—	10 ‡	35 ‡	ns	
22	TinHL	INT pin high or low time	25 *	—	—	ns	
23	TrbHL	RB7:RB0 change INT high or low time	25 *	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

Note 1: Measurements are taken in EC Mode where OSC2 output = 4 x TOSC = TCY.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 18-13: WDT TIMER TIME-OUT PERIOD vs. VDD

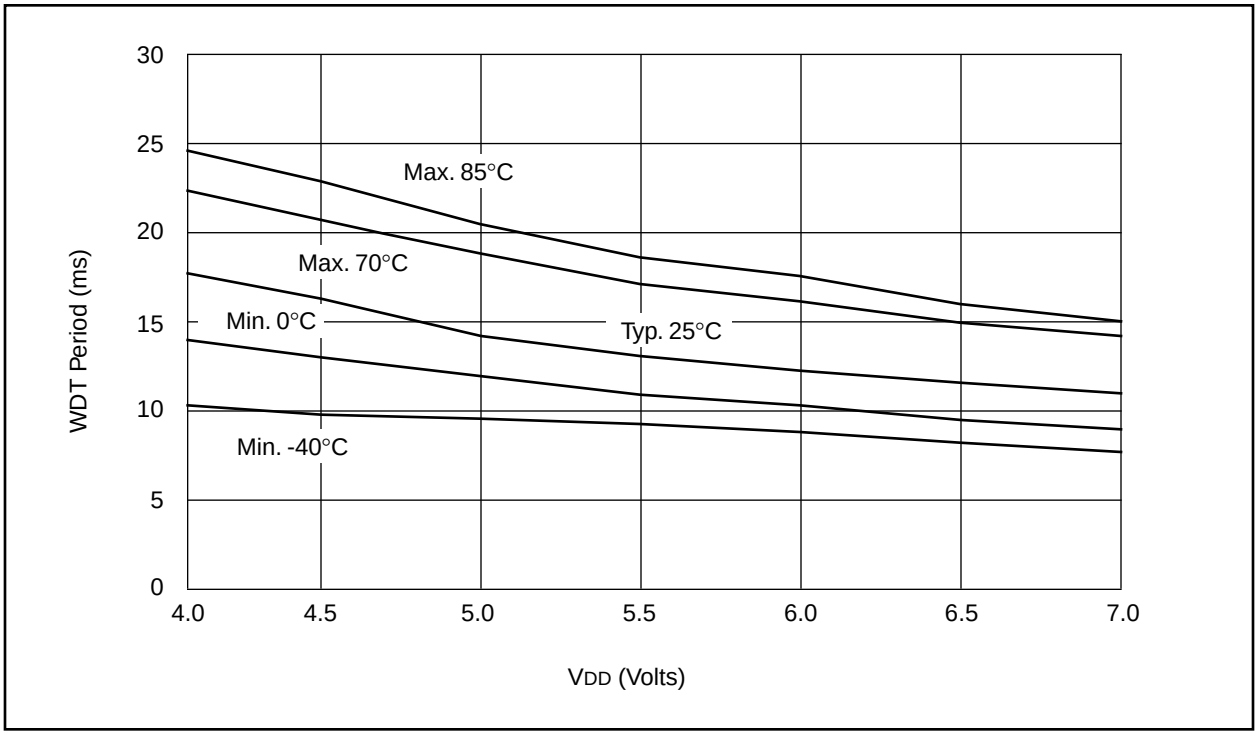
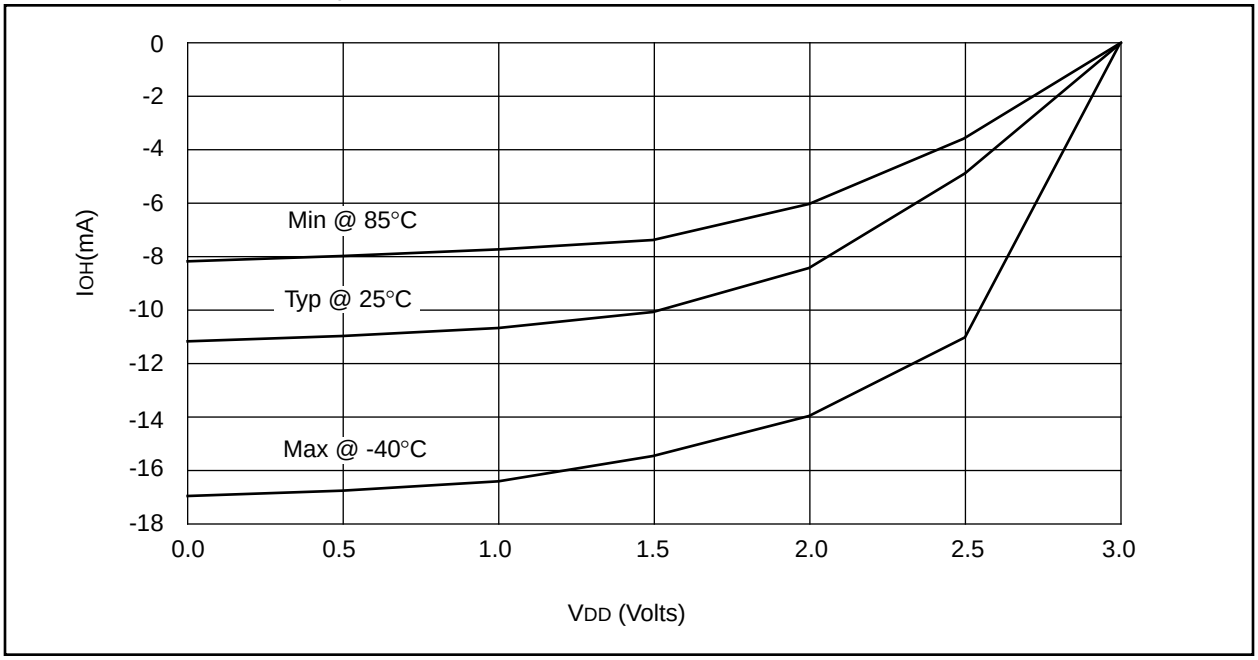


FIGURE 18-14: IOH vs. VOH, VDD = 3V



Applicable Devices	42	R42	42A	43	R43	44

19.2 DC CHARACTERISTICS: PIC17LC42A/43/LC44 (Commercial, Industrial) PIC17LCR42/43 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	2.5	–	6.0	V	
D002	VDR	RAM Data Retention Voltage (Note 1)	1.5 *	–	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure internal Power-on Reset signal	–	VSS	–	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure internal Power-on Reset signal	0.060 *	–	–	mV/ms	See section on Power-on Reset for details
D010	IDD	Supply Current (Note 2)	–	3	6	mA	FOSC = 4 MHz (Note 4)
D011			–	6	12 *	mA	FOSC = 8 MHz
D014			–	95	150	µA	FOSC = 32 kHz, WDT disabled (EC osc configuration)
D020	IPD	Power-down Current (Note 3)	–	10	40	µA	VDD = 5.5V, WDT enabled
D021			–	< 1	5	µA	VDD = 5.5V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1=external square wave, from rail to rail; all I/O pins tristated, pulled to VDD or VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.
Current consumed from the oscillator and I/O's driving external capacitive or resistive loads needs to be considered.
For the RC oscillator, the current through the external pull-up resistor (R) can be estimated as: VDD / (2 • R).
For capacitive loads, the current can be estimated (for an individual I/O pin) as (CL • VDD) • f
CL = Total capacitive load on the I/O pin; f = average frequency the I/O pin switches.
The capacitive currents are most significant when the device is configured for external execution (includes extended microcontroller mode).

3: The power down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula IR = VDD/2Rext (mA) with Rext in kOhm.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 19-11: MEMORY INTERFACE WRITE TIMING (NOT SUPPORTED IN PIC17LC4X DEVICES)

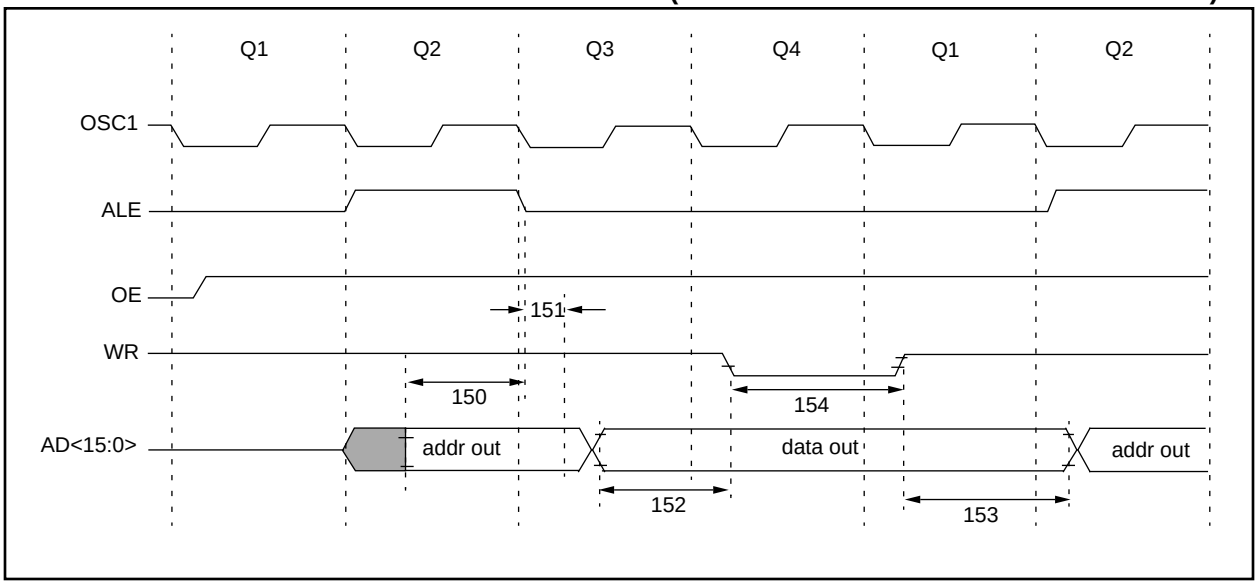


TABLE 19-11: MEMORY INTERFACE WRITE REQUIREMENTS (NOT SUPPORTED IN PIC17LC4X DEVICES)

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
150	TadV2alL	AD<15:0> (address) valid to ALE↓ (address setup time)	0.25Tcy - 10	—	—	ns	
151	TalL2adI	ALE↓ to address out invalid (address hold time)	0	—	—	ns	
152	TadV2wrL	Data out valid to $\overline{WR}$↓ (data setup time)	0.25Tcy - 40	—	—	ns	
153	TwrH2adI	$\overline{WR}$↑ to data out invalid (data hold time)	—	0.25TCY §	—	ns	
154	TwrL	$\overline{WR}$ pulse width	—	0.25TCY §	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 19-12: MEMORY INTERFACE READ TIMING (NOT SUPPORTED IN PIC17LC4X DEVICES)

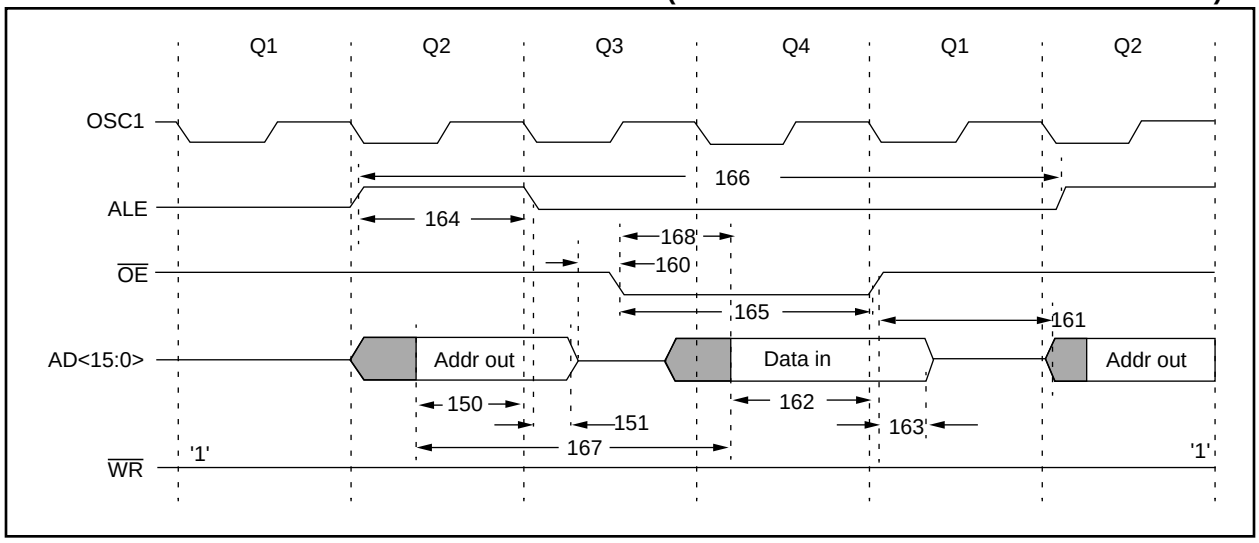


TABLE 19-12: MEMORY INTERFACE READ REQUIREMENTS (NOT SUPPORTED IN PIC17LC4X DEVICES)

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
150	TadV2alL	AD15:AD0 (address) valid to ALE↓ (address setup time)	0.25Tcy - 10	—	—	ns	
151	TalL2adI	ALE↓ to address out invalid (address hold time)	5*	—	—	ns	
160	TadZ2oeL	AD15:AD0 hi-impedance to $\overline{OE}$↓	0*	—	—	ns	
161	ToeH2adD	$\overline{OE}$↑ to AD15:AD0 driven	0.25Tcy - 15	—	—	ns	
162	TadV2oeH	Data in valid before $\overline{OE}$↑ (data setup time)	35	—	—	ns	
163	ToeH2adI	$\overline{OE}$↑to data in invalid (data hold time)	0	—	—	ns	
164	TalH	ALE pulse width	—	0.25TCY §	—	ns	
165	ToeL	$\overline{OE}$ pulse width	0.5Tcy - 35 §	—	—	ns	
166	TalH2alH	ALE↑ to ALE↑(cycle time)	—	TCY §	—	ns	
167	Tacc	Address access time	—	—	0.75TCY - 30	ns	
168	Toe	Output enable access time ($\overline{OE}$ low to Data Valid)	—	—	0.5TCY - 45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

NOTES:

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-7: TYPICAL IDD vs. FREQUENCY (EXTERNAL CLOCK 25°C)

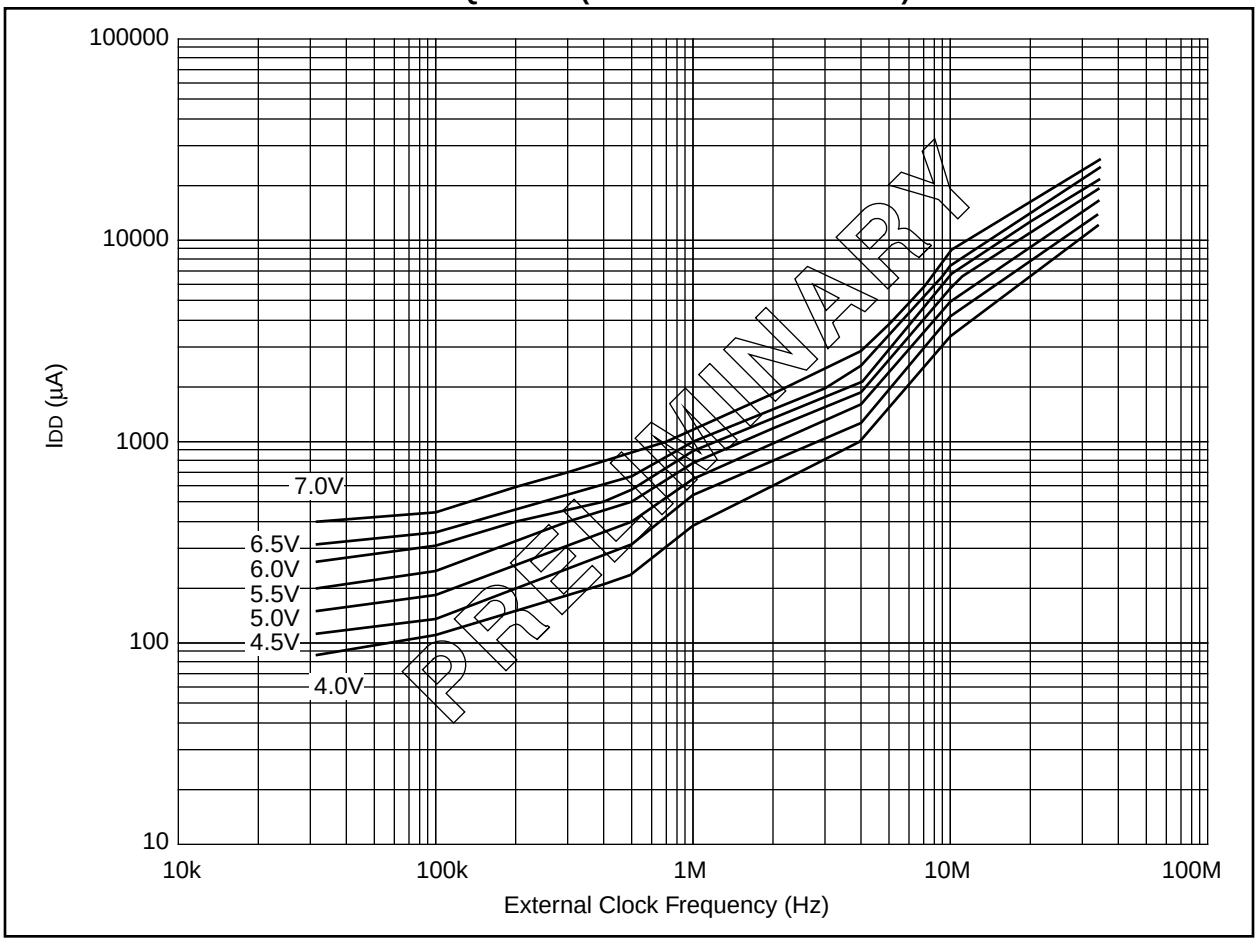
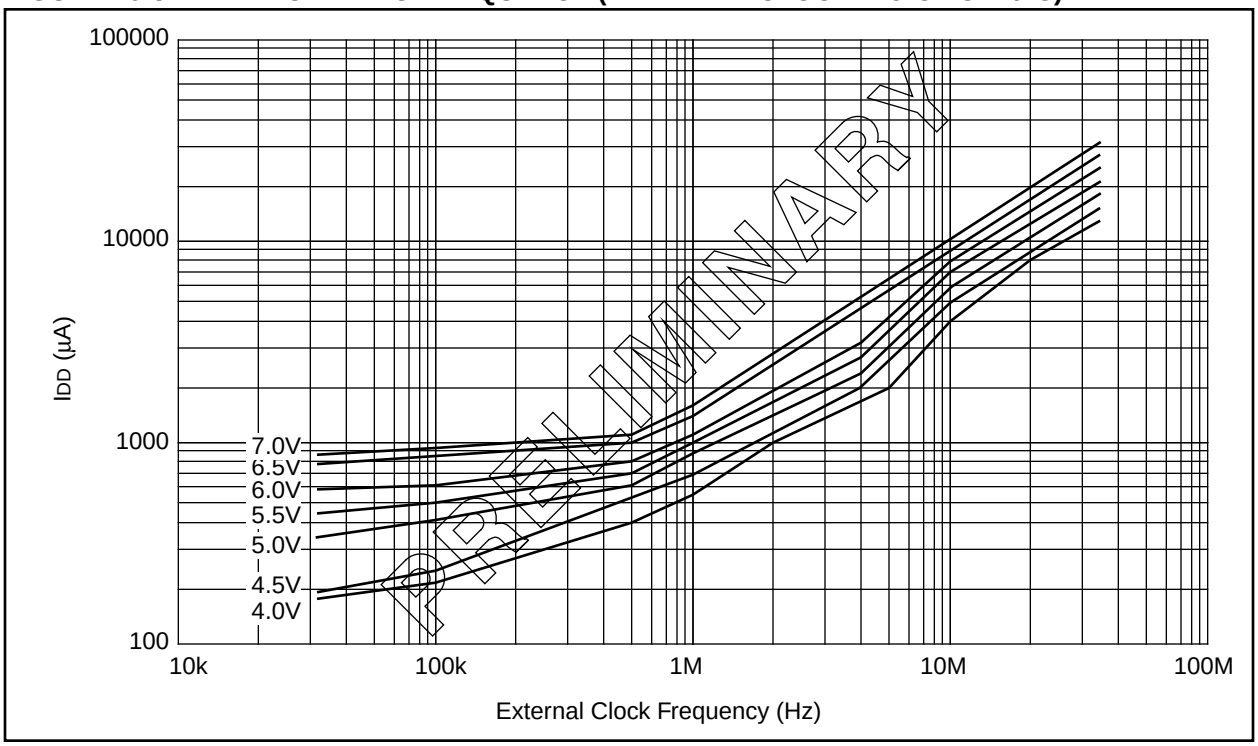
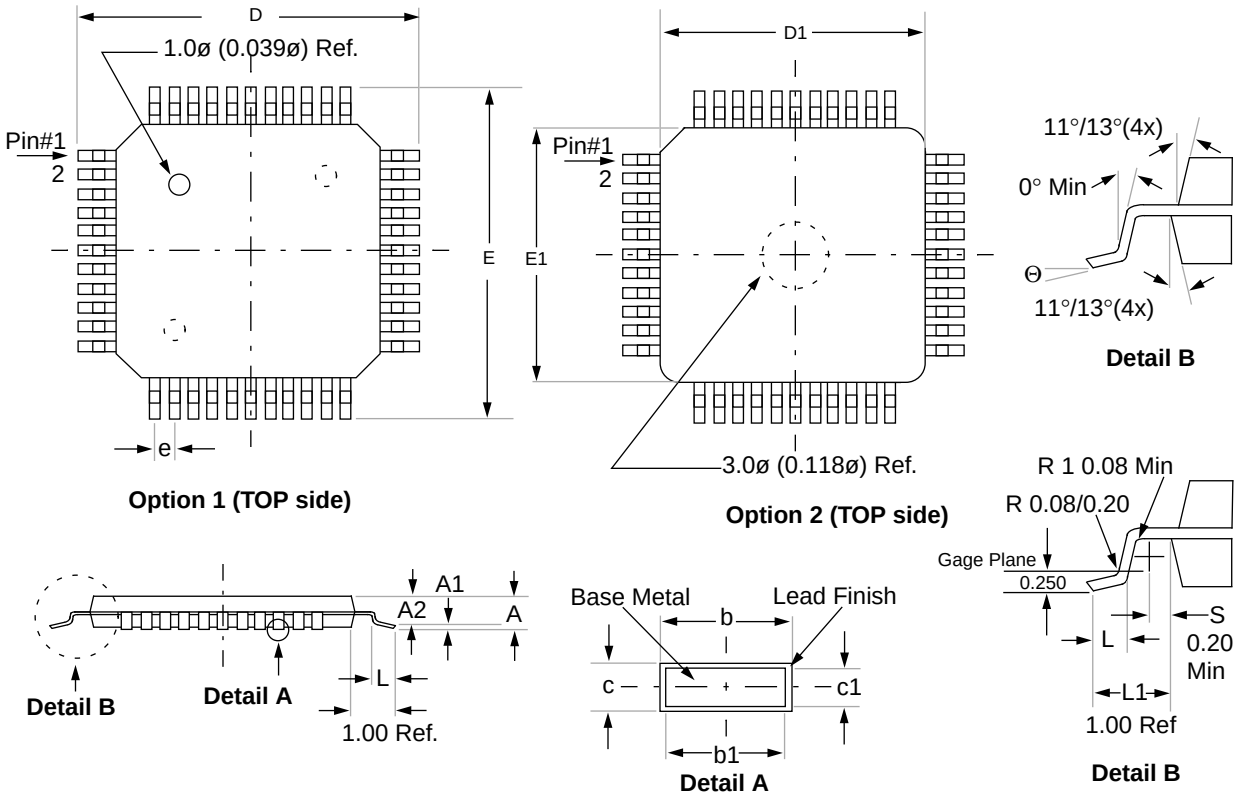


FIGURE 20-8: MAXIMUM IDD vs. FREQUENCY (EXTERNAL CLOCK 125°C TO -40°C)



21.5 44-Lead Plastic Surface Mount (TQFP 10x10 mm Body 1.0/0.10 mm Lead Form)



Package Group: Plastic TQFP						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
A	1.00	1.20		0.039	0.047	
A1	0.05	0.15		0.002	0.006	
A2	0.95	1.05		0.037	0.041	
D	11.75	12.25		0.463	0.482	
D1	9.90	10.10		0.390	0.398	
E	11.75	12.25		0.463	0.482	
E1	9.90	10.10		0.390	0.398	
L	0.45	0.75		0.018	0.030	
e	0.80 BSC			0.031 BSC		
b	0.30	0.45		0.012	0.018	
b1	0.30	0.40		0.012	0.016	
c	0.09	0.20		0.004	0.008	
c1	0.09	0.16		0.004	0.006	
N	44	44		44	44	
Θ	0°	7°		0°	7°	

Note 1: Dimensions D1 and E1 do not include mold protrusion. Allowable mold protrusion is 0.25m/m (0.010”) per side. D1 and E1 dimensions including mold mismatch.

2: Dimension “b” does not include Dambar protrusion, allowable Dambar protrusion shall be 0.08m/m (0.003”)max.

3: This outline conforms to JEDEC MS-026.

X

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LIST OF EXAMPLES

LIST OF FIGURES

Note the following details of the code protection feature on PICmicro® MCUs.

- The PICmicro family meets the specifications contained in the Microchip Data Sheet.
- Microchip believes that its family of PICmicro microcontrollers is one of the most secure products of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the PICmicro microcontroller in a manner outside the operating specifications contained in the data sheet. The person doing so may be engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable”.
- Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our product.

If you have any further questions about this matter, please contact the local sales office nearest to you.

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Microchip received QS-9000 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona in July 1999. The Company’s quality system processes and procedures are QS-9000 compliant for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs and microperipheral products. In addition, Microchip’s quality system for the design and manufacture of development systems is ISO 9001 certified.